### 查询SN75LP196供应商

# 捷多邦,专业PCB打样工厂,24小时加急出货SN75LP196 LOW-POWER MULTIPLE RS-232 DRIVERS AND RECEIVERS

- Single-Chip RS-232 Interface for an External Modem or Other Computer Peripheral Serial Port
- Designed to Transmit and Receive 4-μs Pulses (Equivalent to 256 kbit/s)
- Wide Driver Supply-Voltage Range: 4.75 V to 15 V
- Driver Output Slew Rates Are Controlled Internally to 30 V/µs Maximum
- Receiver Input Hysteresis . . . 1000 mV Typical
- RS-232 Bus-Pin ESD Protection Exceeds 15 kV Using Human-Body Model (HBM)
- Five Drivers and Three Receivers Meet or Exceed the Requirements of TIA/EIA-232-F and ITU v.28 Standards
- Complements the SN75LP1185
- Designed to Replace the Industry-Standard SN75196 With the Same Flow-Through Pinout
- Package Options Include Plastic Small Outline (DW), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), and Dual-in-Line (N) Packages

### description

The SN75LP196 is a low-power bipolar device containing five drivers and three receivers, with 15 kV of ESD protection on the bus pins with respect to each other. Bus pins are defined as those pins that tie directly to the serial-port connector, including GND. The pinout matches the flow-through design of the industry-standard SN75196 and allows easy interconnection of the UART and serial-port connector of the IBM PC/AT and compatibles. This device provides a rugged, low-cost solution for this function with the combination of bipolar processing and 15-kV ESD protection.

The SN75LP196 has internal slew-rate control to provide a maximum rate of change in the output signal of 30 V/ $\mu$ s. The driver output swing is clamped nominally at ±6 V to enable the higher data rates associated with this device and to reduce EMI emissions. Even though the driver outputs are clamped, they can handle voltages up to ±15 V without damage. All the logic inputs can accept 3.3-V or 5-V input signals.

The SN75LP196 complies with the requirements of the TIA/EIA-232-F and the ITU v.28 standards. These standards are for data interchange between a host computer and peripheral at signaling rates up to 20 kbit/s. The switching speeds of the SN75LP196 support rates up to 256 kbit/s with lower capacitive loads (shorter cables).

The SN75LP196 is characterized for operation from 0°C to 70°C.

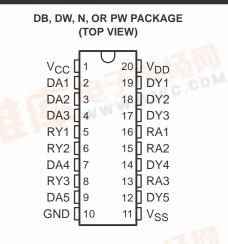


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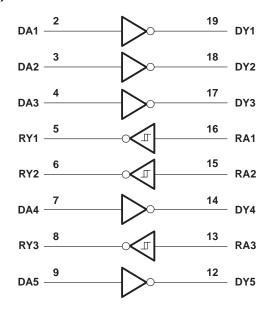
SLLS294A - APRIL 1998 - REVISED JUNE 1999

### **Function Tables**

DRIVER							
INPUT DA	OUTPUT DY						
Н	L						
L	н						
Open	L						

RECEIVER							
INPUT RA	OUTPUT RY						
Н	L						
L	Н						
Open	Н						

# logic diagram (positive logic)



SLLS294A - APRIL 1998 - REVISED JUNE 1999

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Positive supply-voltage range (see Note 1): V <sub>CC</sub> V <sub>DD</sub> (see Note 1)	
Negative supply-voltage range, V <sub>SS</sub> (see Note 1)	0.5 V to –15 V
Input-voltage range, V <sub>I</sub> : Receiver (RA) Driver (DA)	$\dots \dots -0.5$ V to V <sub>CC</sub> +0.4 V
Output-voltage range, V <sub>O</sub> : Receiver (RY) Driver (DY)	
Electrostatic discharge: Bus pins (human-body model) (see Note 2)	Class 3, A: 15 kV
All pins (human-body model) (see Note 2)   All pins (machine model)	
N package	
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values are with respect to network ground terminal, unless otherwise noted.

2. Per MIL-STD-883 Method 3015.7

3. Maximum power dissipation is a function of  $T_J(max)$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(max) - T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can impact reliability.

4. The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

		MIN	NOM	MAX	UNIT
Supply voltage (see Note 5)		4.75	5	5.25	V
Supply voltage (see Note 6)		9	12	15	V
Supply voltage (see Note 6)		-9	-12	-15	V
High-level input voltage	DA	2			V
Low-level input voltage	DA			0.8	V
Receiver input voltage	RA	-25		25	V
High-level output current	RY			-1	mA
Low-level output current	RY			2	mA
Operating free-air temperature		0		70	°C
	Supply voltage (see Note 6) Supply voltage (see Note 6) High-level input voltage Low-level input voltage Receiver input voltage High-level output current Low-level output current	Supply voltage (see Note 6)   Supply voltage (see Note 6)   High-level input voltage DA   Low-level input voltage DA   Receiver input voltage RA   High-level output current RY   Low-level output current RY	Supply voltage (see Note 5)4.75Supply voltage (see Note 6)9Supply voltage (see Note 6)-9High-level input voltageDA2Low-level input voltageDA2Receiver input voltageRA-25High-level output currentRY	Supply voltage (see Note 5)4.755Supply voltage (see Note 6)912Supply voltage (see Note 6)-9-12High-level input voltageDA2Low-level input voltageDA2Receiver input voltageRA-25High-level output currentRY-12	$\begin{array}{c c c c c c c c c c c c c c c c c c c $

### recommended operating conditions

NOTES: 5.  $V_{CC}$  cannot be greater than  $V_{DD}$ .

6. The device operates down to V<sub>DD</sub> = V<sub>CC</sub> and |V<sub>SS</sub>| = V<sub>CC</sub>, but supply currents increase and other parameters may vary slightly from the data-sheet limits.



SLLS294A - APRIL 1998 - REVISED JUNE 1999

### supply currents over the recommended operating conditions (unless otherwise noted)

PARAMETER	TEST CONDITIONS			TYP	MAX	UNIT
		$V_{DD} = 9 V$ , $V_{SS} = -9 V$			1000	μA
Supply current for V <sub>CC</sub> , I <sub>CC</sub>	No load.	$V_{DD} = 12 \text{ V},  V_{SS} = -12 \text{ V}$			1000	μΑ
	All inputs at	$V_{DD} = 9 V$ , $V_{SS} = -9 V$			800	
Supply current for V <sub>DD</sub> , I <sub>DD</sub>	minimum V <sub>OH</sub> or	$V_{DD} = 12 \text{ V},  V_{SS} = -12 \text{ V}$			800	μA
	maximum V <sub>OL</sub>	$V_{DD} = 9 V$ , $V_{SS} = -9 V$			-800	
Supply current for VSS, ISS		$V_{DD} = 12 \text{ V},  V_{SS} = -12 \text{ V}$			-800	μA

# driver electrical characteristics over the recommended operating conditions (unless otherwise noted)

	PARAMETER		TEST CON	DITIONS		MIN	TYP	MAX	UNIT
Vou	High-level output voltage	$V_{IL} = 0.8 V,$	V <sub>DD</sub> = 9 V,	$V_{SS} = -9 V,$	See Note 7	5	5.8	6.6	V
VOH	nigh-level output voltage	$R_L = 3 k\Omega$ , See Figure 1	V <sub>DD</sub> = 12 V,	$V_{SS} = -12 V$ ,	See Note 8	5	5.8	6.6	v
Vei	Low-level output voltage	$V_{IH} = 2 V,$ By $= 2 kO$	V <sub>DD</sub> = 9 V,	$V_{SS} = -9 V,$	See Note 7	-5	-5.8	-6.9	V
VOL	Low-level output voltage	$R_L = 3 k\Omega$ , See Figure 1	V <sub>DD</sub> = 12 V,	$V_{SS} = -12 V_{,}$	See Note 8	-5	-5.8	-6.9	v
Ιн	High-level input current	VI at V <sub>CC</sub>					1	μA	
١ <sub>IL</sub>	Low-level input current	V <sub>I</sub> at GND					-1	μΑ	
IOS(H)	Short-circuit high-level output current	$V_{O} = GND \text{ or } V_{SS}$	3	See Figure 2 a	nd Note 9		-30	-55	mA
IOS(L)	Short-circuit low-level output current	$V_{O} = GND \text{ or } V_{DD},$		See Figure 2 a	nd Note 9		30	55	mA
r <sub>o</sub>	Output resistance	$V_{DD} = V_{SS} = V_{CC}$	; = 0,	$V_{O} = -2 V \text{ to } 2$	V	300			Ω

NOTES: 7. Minimum RS-232 driver output voltages are not attained with  $\pm$ 5-V supplies. With V<sub>DD</sub> less than V<sub>CC</sub> + 2 V, the supply currents may increase. For RS-232 compliant output swings and minimum power consumption, V<sub>DD</sub>  $\geq$  V<sub>CC</sub> + 2 V.

8. Maximum output swing is nominally clamped at ±6 V to enable the higher data rates associated with this device and to reduce EMI emissions. The driver outputs may slightly exceed the maximum output voltage over the full V<sub>CC</sub> and temperature ranges.

9. Not more than one output should be shorted at one time.



SLLS294A - APRIL 1998 - REVISED JUNE 1999

# driver switching characteristics over operating free-air temperature range (unless otherwise noted)

	PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT		
<sup>t</sup> PHL	Propagation delay time, high- to low-level output	$R_L = 3 \text{ k}\Omega \text{ to } 7 \text{ k}\Omega, C$	R <sub>L</sub> = 3 k $\Omega$ to 7 k $\Omega$ , C <sub>L</sub> = 15 pF, See Figure 1			1600	ns		
<sup>t</sup> PLH	Propagation delay time, low- to high-level output	$R_L = 3 k\Omega$ to 7 kΩ, C	$R_L$ = 3 k $\Omega$ to 7 k $\Omega$ , $C_L$ = 15 pF, See Figure 1			1600	ns		
		$V_{CC} = 5 V,$ $V_{DD} = 12 V,$	Using $V_{TR}$ = 10%-to-90% transition region, Driver speed = 250 kbit/s, C <sub>L</sub> = 15 pF	375		2240			
t <sub>TLH</sub>	Transition time, low- to high-level output	$V_{SS} = -12 V$ , $R_L = 3 k\Omega$ to 7 k $\Omega$ ,	$V_{SS} = -12 V,$	$V_{SS} = -12 V_{,}$	Using V <sub>TR</sub> = $\pm$ 3 V transition region, Driver speed = 250 kbit/s, C <sub>L</sub> = 15 pF	200		1500	ns
	See Figure 1 and Note 10	Using V <sub>TR</sub> = $\pm$ 3 V transition region, Driver speed = 125 kbit/s, C <sub>L</sub> = 2500 pF			2750				
		$V_{CC} = 5 V,$ $V_{DD} = 12 V,$	Using $V_{TR}$ = 10%-to-90% transition region, Driver speed = 250 kbit/s, C <sub>L</sub> = 15 pF	375		2240			
t <sub>THL</sub>	Transition time, high- to low-level output	$V_{SS} = -12 \text{ V},$ R <sub>L</sub> = 3 k $\Omega$ to 7 k $\Omega$ ,	Using V <sub>TR</sub> = $\pm$ 3 V transition region, Driver speed = 250 kbit/s, C <sub>L</sub> = 15 pF	200		1500	ns		
		See Figure 1 and Note 10	Using V <sub>TR</sub> = $\pm$ 3 V transition region, Driver speed = 125 kbit/s, C <sub>L</sub> = 2500 pF			2750			
SR	Output slew rate	V <sub>CC</sub> = 5 V, V <sub>DD</sub> = 12 V, V <sub>SS</sub> = -12 V,	Using V <sub>TR</sub> = $\pm$ 3 V transition region, Driver speed = 0 to 250 kbit/s, C <sub>L</sub> = 15 pF	4	20	30	V/µs		

NOTE 10: Maximum output swing is limited to ±6 V to enable the higher data rates associated with this device and to reduce EMI emissions.

# receiver electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST	CONDITIONS	MIN	TYP	MAX	UNIT
V <sub>IT+</sub>	Positive-going input threshold voltage	See Figure 3		1.6	2	2.55	V
VIT-	Negative-going input threshold voltage	See Figure 3		0.6	1	1.45	V
VHYS	Input hysteresis, VIT+ VIT-	See Figure 3		750	1000		mV
VOH	High-level output voltage	$I_{OH} = -1 \text{ mA}$		2.5	3.9		V
VOL	Low-level output voltage	$I_{OL} = 2 \text{ mA}$			0.33	0.5	V
1	High-level input current	V <sub>I</sub> = 3 V		0.43	0.6	1	mA
ΊΗ	High-level liput current	V <sub>I</sub> = 25 V		3.6	5.1	8.3	ША
1	Low-level input current	V <sub>I</sub> = 3 V		-0.43	-0.6	-1	mA
ΊL	Low-level input current	V <sub>I</sub> = 25 V		-3.6	-5.1	-8.3	IIIA
IOS(H)	Short-circuit high-level output current	$V_{O} = 0,$	See Figure 5 and Note 9			-20	mA
IOS(L)	Short-circuit low-level output current	$V_{O} = V_{CC},$	See Figure 5 and Note 9			20	mA
R <sub>IN</sub>	Input resistance	$V_I = \pm 3 V$ to $\pm 25 V$		3	5	7	kΩ

NOTE 9: Not more than one output should be shorted at one time.

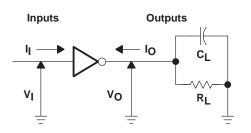


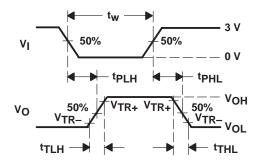
SLLS294A - APRIL 1998 - REVISED JUNE 1999

receiver switching characteristics over operating free-air temperature range,  $C_L = 50 \text{ pF}$  (unless otherwise noted) (see Figure 4)

	PARAMETER	MIN	TYP	MAX	UNIT
t <sub>PHL</sub>	Propagation delay time, high- to low-level output		400	900	ns
<sup>t</sup> PLH	Propagation delay time, low- to high-level output		400	900	115
<sup>t</sup> TLH	Transition time, low- to high-level output		200	450	50
<sup>t</sup> THL	Transition time, high- to low-level output		200	400	ns
<sup>t</sup> sk(p)	Pulse skew  tpLH - tpHL		200	425	ns

### PARAMETER MEASUREMENT INFORMATION

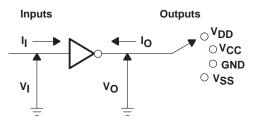




NOTES: A. The pulse generator has the following characteristics: For C<sub>L</sub> < 1000 pF: t<sub>W</sub> = 4 µs, PRR = 250 kbit/s, Z<sub>O</sub> = 50  $\Omega$ , t<sub>r</sub> = t<sub>f</sub> < 50 ns. For C<sub>L</sub> = 2500 pF: t<sub>W</sub> = 8 µs, PRR = 125 kbit/s, Z<sub>O</sub> = 50  $\Omega$ , t<sub>r</sub> = t<sub>f</sub> < 50 ns.

B.  $C_L$  includes probe and jig capacitance.

### Figure 1. Driver Parameter Test Circuit and Waveform





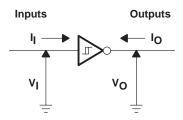


Figure 3. Receiver VIT Test



ttlh ->

SLLS294A - APRIL 1998 - REVISED JUNE 1999

– <sup>t</sup>THL

#### PARAMETER MEASUREMENT INFORMATION 4 V ٧ı 50% 50% Inputs Outputs 0 V **t**PLH <sup>t</sup>PHL 16 ۷он 90% 90% ٧o 50% 50% CL <u>10%</u> V<sub>OL</sub> ٧<sub>0</sub> 10% ٧ı

NOTES: A. The pulse generator has the following characteristics:  $t_W = 4 \mu s$ , PRR = 250 kbit/s,  $Z_O = 50 \Omega$ ,  $t_r = t_f < 50 ns$ . B. CL includes probe and jig capacitance.



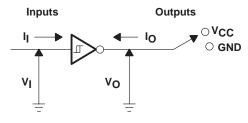


Figure 5. Receiver I<sub>OS</sub> Test

### **APPLICATION INFORMATION**

Diodes placed in series with the V<sub>DD</sub> and V<sub>SS</sub> leads protect the SN75LP196 in the fault condition in which the device outputs are shorted to  $\pm$ 15 V and the power supplies are at low voltage and provide low-impedance paths to ground (see Figure 6).

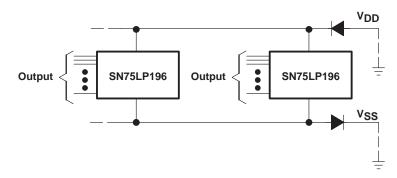


Figure 6. Power-Supply Protection to Meet Power-Off Fault Conditions of EIA/TIA-232-F



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